

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of:

	Stephan Grunow et al.	Docket No.:	TI-35917
Serial No:	10/688,452	Art Unit:	3726
Filed:	10/18/2003	Examiner:	Rick K. Chang
Customer No.:	23494	Conf. No.:	1572
Title:	A Method of Forming a Stacked Interconnect Structure Between Copper Lines of a Semiconductor Circuit		

**RESPONSE UNDER 37 CFR 1.111**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

The following remarks are offered in response to the Examiner's Office Action dated July 18, 2007. They are respectfully submitted as a full and complete response to that Action.

**REMARKS**

Reconsideration of the above-referenced application in view of the following remarks is respectfully requested.

Claims 1-12 are pending in this case.